

# POSITIVE PHOTSENSITIVE RESIN COMPOSITION, CURED FILM FORMED FROM SAME, AND ELEMENT HAVING CURED FILM

## Abstract

Disclosed is a positive photosensitive resin composition which contains a polysiloxane (a), a naphthoquinone diazide compound (b) and a solvent (c). The positive photosensitive resin composition is characterized in that the polysiloxane (a) has: an organosilane-derived structure represented by general formula (1) at a content ratio of 20-80% inclusive of Si relative to the overall number of moles of Si atoms in the polysiloxane; and an organosilane-derived structure represented by general formula (2). The positive photosensitive resin composition exhibits high heat resistance, high transparency, and enables high sensitivity, high resolution patterning. The positive photosensitive resin composition can be used to form cured films such as planarization films used in TFT substrates, interlayer insulating films, core materials and cladding materials, and can be used in elements having cured films such as display elements, semiconductor elements, solid-state imaging elements, and optical waveguide elements.

